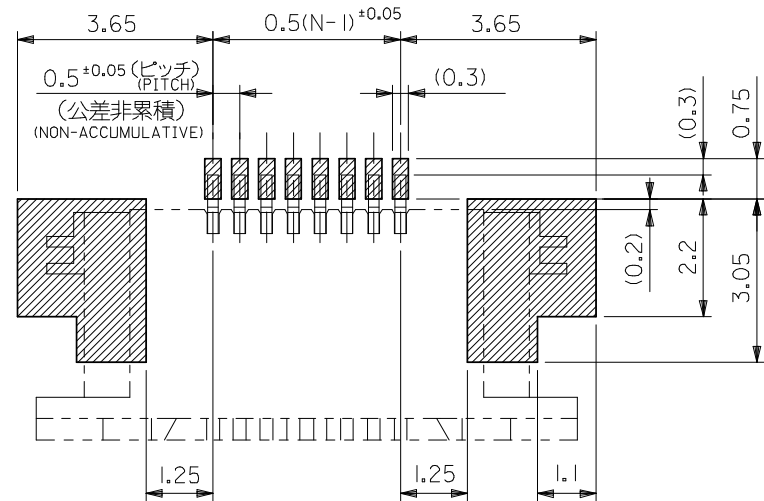


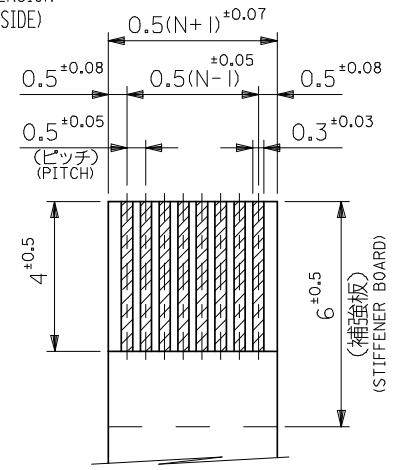
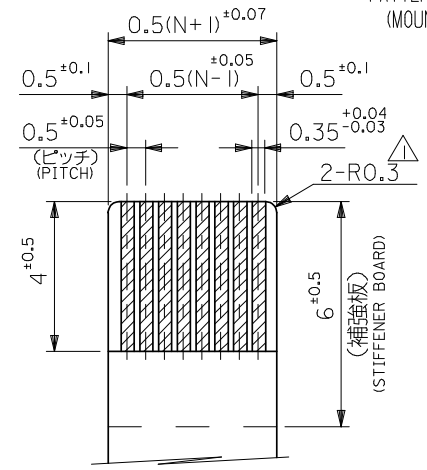
- 注記(NOTES)
- 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE t=0.2
鍍ビスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH I.O. MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM
 - ハウジング (HOUSING): 46ナイロン (46NYLON), UL94V-0
 - 金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE t=0.2
鍍メッキ 1. 0マイクロメートル以上
TIN I.O. MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM
 - ③ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX.、下方向 0.15MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
 - ④ 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 - 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

REVISED EC NO: J2008-4308 DRWN: MWABEI 2008/06/27 CHKD: THARUYAMA 2008/06/30 APPR: NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	DOCUMENT NO. SD-52689-034		SHEET NO. 1 OF 2	
	ANGULAR ±3		MATERIAL NO. SEE SHEET 2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参考基板レイアウト
(マウント面)

REFERENCE P.C.BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合F P C推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.03)
(THICKNESS: 0.3 ± 0.03)

適合F F C推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.03)
(THICKNESS: 0.3 ± 0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

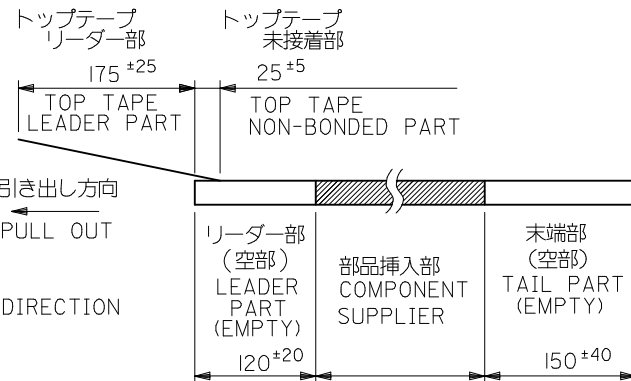
17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2008-4308 DRWN:WABEI 2008/06/27 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	DOCUMENT NO. SD-52689-034			
	ANGULAR	±3 °	MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

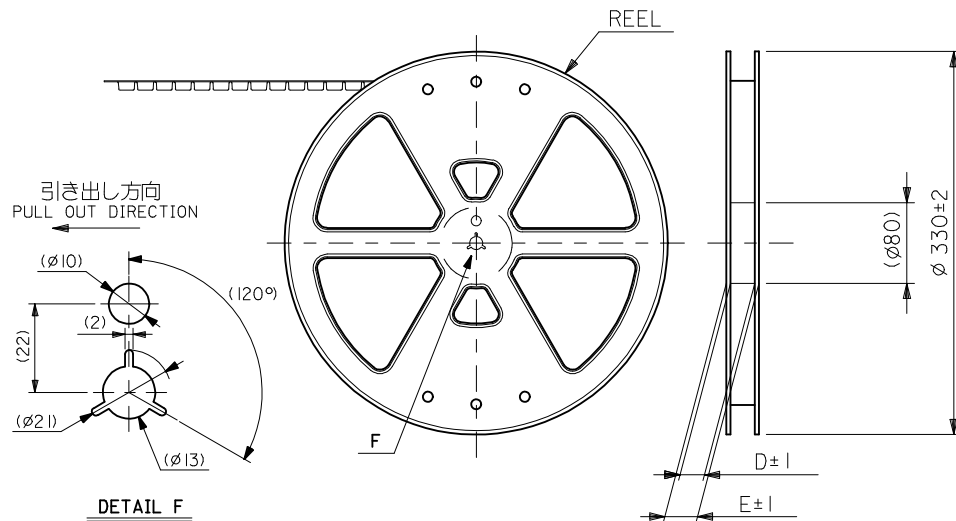
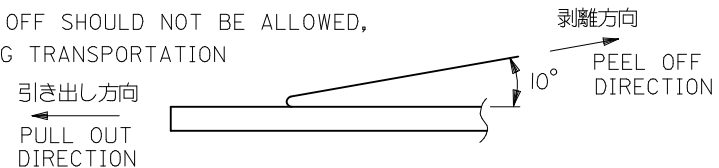
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

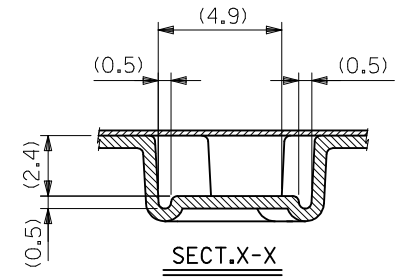
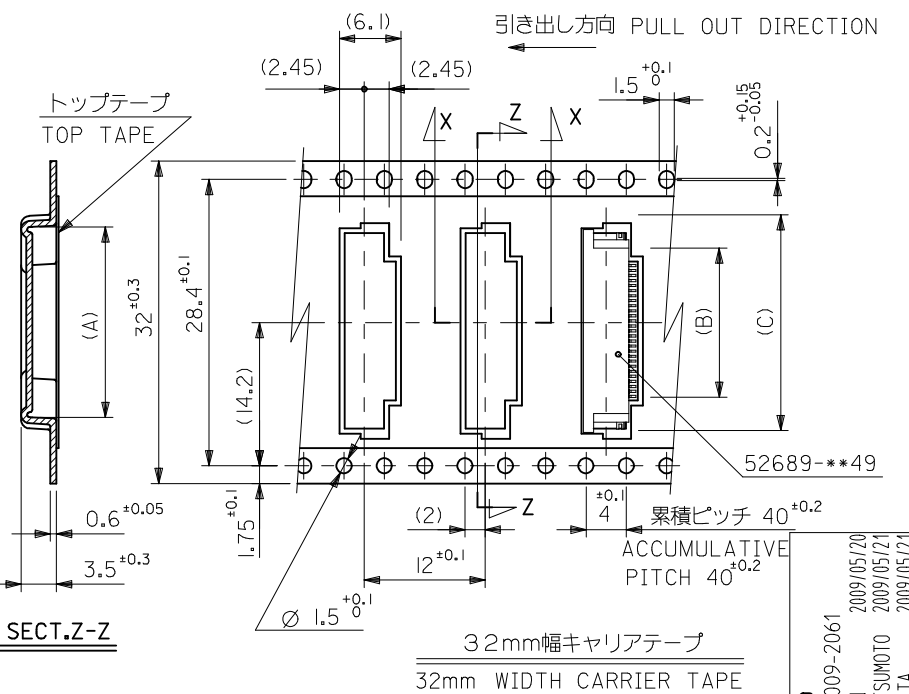
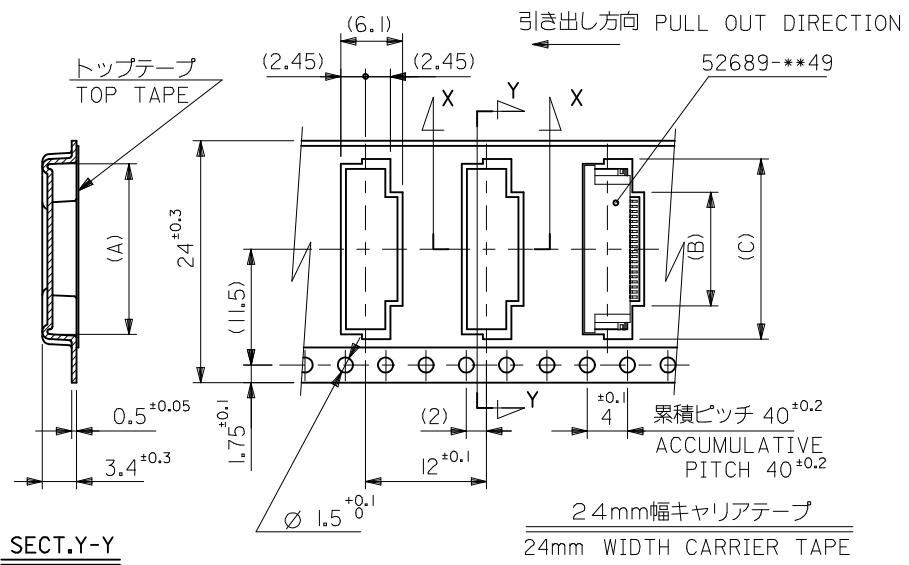
- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

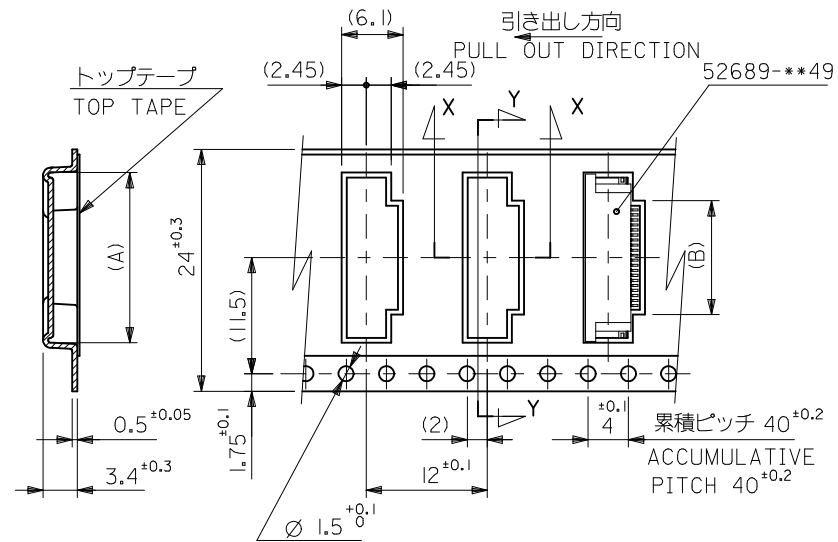
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO.: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NIKIITA 2009/05/21 REV: A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO	DATE 2004/02/03	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2004/02/03	DOCUMENT NO. SD-52689-035	SHEET NO. 1 OF 3	
	ANGULAR ±3°	MATERIAL NO. SEE SHEET 2,3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						



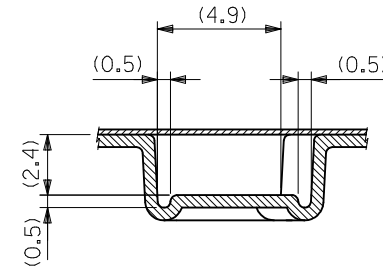
32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
			21.9	15.3	20.9	-2987	29
			21.4	14.8	20.4	-2887	28
			20.9	14.3	19.9	-2787	27
			20.4	13.8	19.4	-2687	26
			19.9	13.3	18.9	-2587	25
			19.4	12.8	18.4	-2487	24
			18.9	12.3	17.9	-2387	23
			17.9	11.3	16.9	-2187	21
			17.4	10.8	16.4	-2087	20
24	29.4	25.4	16.9	10.3	15.9	-1987	19
			16.4	9.8	15.4	-1887	18
			15.4	8.8	14.4	-1687	16
			14.9	8.3	13.9	-1587	15
			14.4	7.8	13.4	-1487	14
			13.9	7.3	12.9	-1387	13
			13.4	6.8	12.4	-1287	12
			12.9	6.3	11.9	-1187	11
			12.4	5.8	11.4	-1087	10
			11.9	5.3	10.9	-0987	9
11.4	4.8	10.4	-0887	8			
10.9	4.3	9.9	-0787	7			
10.4	3.8	9.4	-0687	6			
9.9	3.3	8.9	52689 -0587	5			

REVISED EC NO: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NIKIITA 2009/05/21	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MODEL NO. 52689-**-87 CARRIER TAPE WIDTH E D	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		DRAWN BY H.KAWABATA CHECKED BY K.TOJO APPROVED BY M.SASAO	DATE 2004/02/03 DATE 2004/02/03 DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52689-035	SHEET NO. 2 OF 3
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	MOLEX INCORPORATED				
		EN-02JA(021)					



SECT.Y-Y

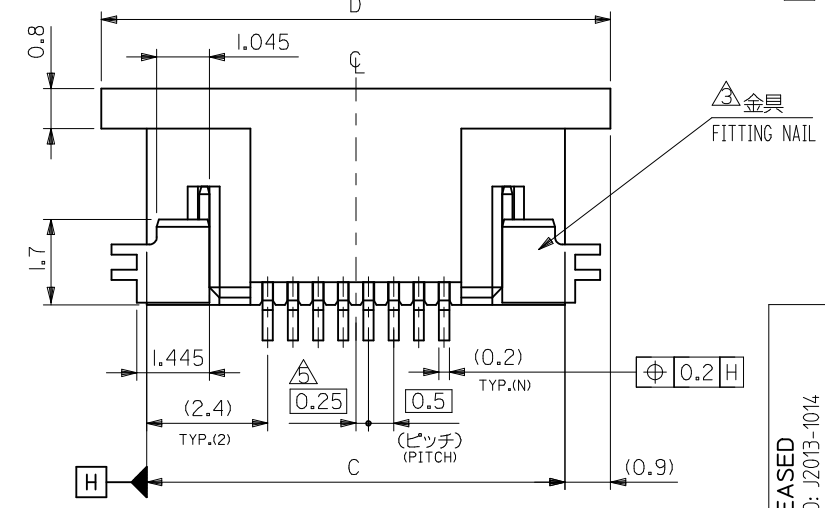
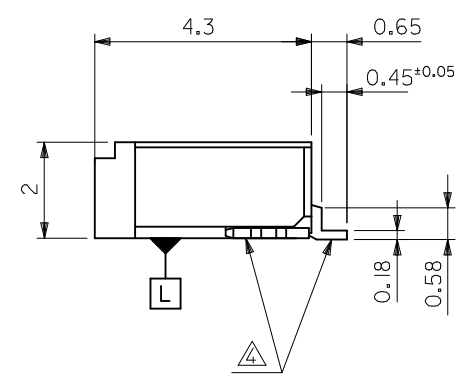
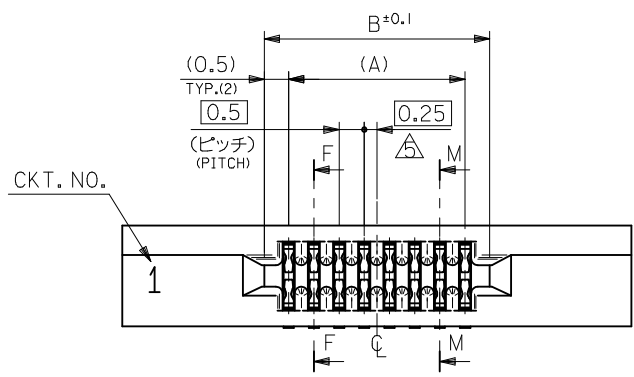
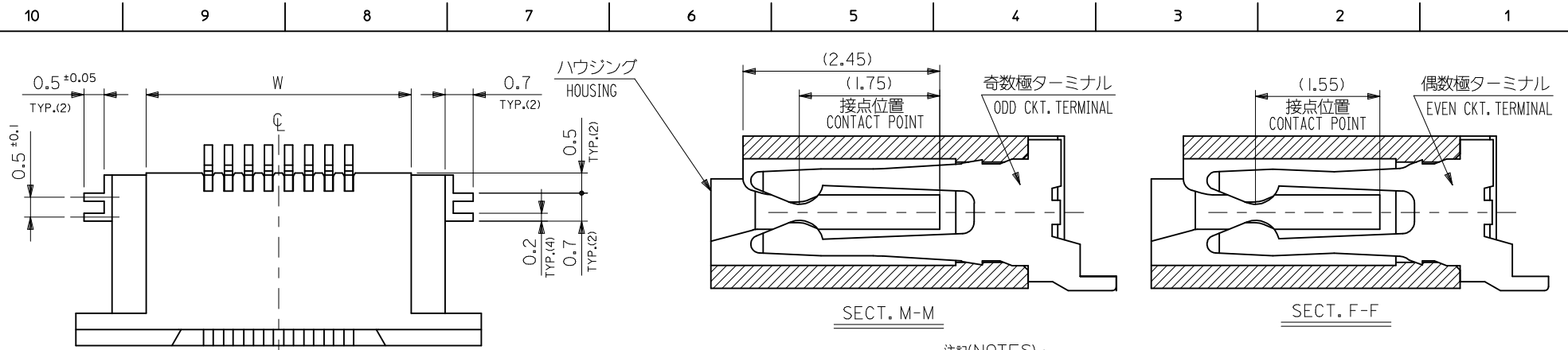
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



SECT.X-X

24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅	E	D	(B)	(A)	MATERIAL NO.
MODEL NO.	CARRIER TAPE WIDTH					極数 CIRCUIT

REVISED EC NO: J2009-2061 DRWN:TKON CHKD:MATSUMOTO APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO	DATE 2004/02/03	APPROVED BY M.SASAO			
		30 OVER	±0.3	DATE 2004/02/03	MATERIAL NO. SEE TABLE				
ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		DOCUMENT NO. SD-52689-035		SHEET NO. 3 OF 3	



- 注記(NOTES):
- 使用材料 MATERIAL
 ターミナル : リン青銅 (t=0.2)
 TERMINAL : PHOSPHOR BRONZE t=0.2
 ハウジング : 46ナイロン, ナチュラル, ガラス充填, UL94V-0
 HOUSING : 46NYLON, NATURAL, GLASS FILLED, UL94V-0
 金具 : リン青銅 (t=0.2)
 FITTING NAIL : PHOSPHOR BRONZE t=0.2
 - めっき仕様 PLATING
 ターミナル TERMINAL
 錫銀ピスマスメッキ (1.0 μm以上)
 TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
 下地: ニッケルめっき (1.0 μm以上)
 UNDER PLATE: NICKEL PLATING (1.0 MICROMETER MINIMUM)
 金具 FITTING NAIL
 錫系メッキ (1.0 μm以上)
 TIN BASED PLATE (1.0 MICROMETER MINIMUM)
 下地: ニッケルめっき (1.0 μm以上)
 UNDER PLATE: NICKEL (1.0 MICROMETER MINIMUM)
 - △ バターン剥離止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING OFF PCB.PATTERN.
 - △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 □ に対し上方向0.1MAX, 下方向0.15MAXとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM □ UPPER DIRECTION 0.1MAX, LOWER DIRECTION 0.15MAX.
 - △ 偶数極に適用。
 TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.
 - △ R0.3は、FPCの導体部にかからないこと。
 R0.3 MUST NOT BE OVER LAPPED TO PATTERN OF FPC.
 - ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT

RELEASED EC NO.: J2013-1014 DRWN: TMORISHITA 2012/09/07 CHKD: KTAKAHASHI 2012/09/10 APPR: KMORIKAWA 2013/03/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/07	TITLE 0.5 FPC CONN NON-ZIF R/A HOUSING ASSY		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/10			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15			
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-52689-049	SHEET NO. 1 OF 2
		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					